

F i g. 2

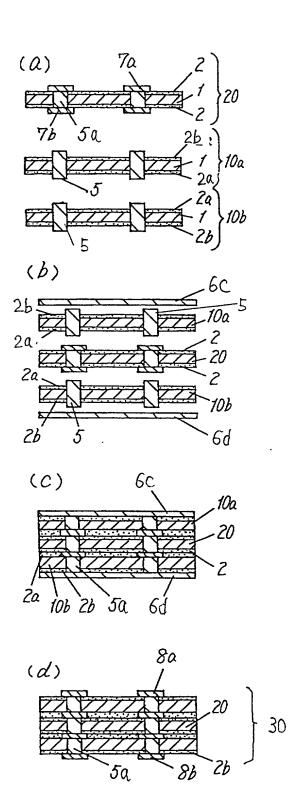


Fig. 2

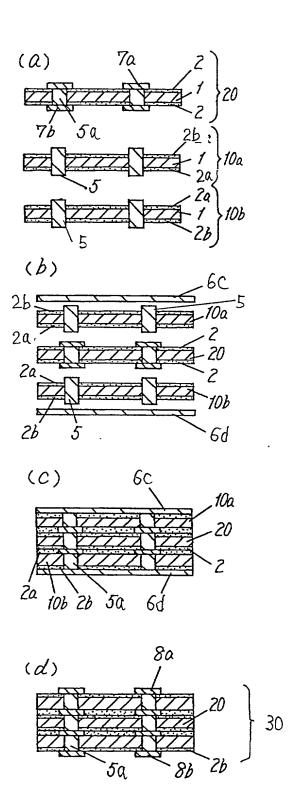
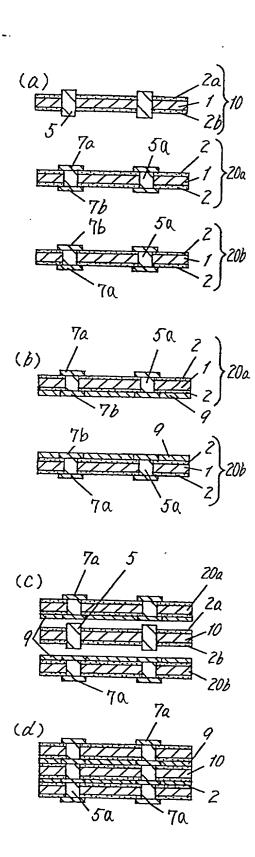


Fig. 4 (a) Bonding layer thickness 5  $\mu m$ resistance Connection Low-High Central portion End Substrate position (b) Bonding layer thickness 10  $\mu m$ Connection resistance Low—▼High Central portion Substrate position (c) Bonding layer thickness 15  $\mu m$ resistance Connection Low-High End Central portion End Substrate position (d) Bonding layer thickness 20  $\mu m$ Connection resistance Low-High Central portion End Substrate position (e) Bonding layer thickness 30  $\mu m$ Connection resistance Low-+High Central portion -End

Substrate position



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F i g. 6

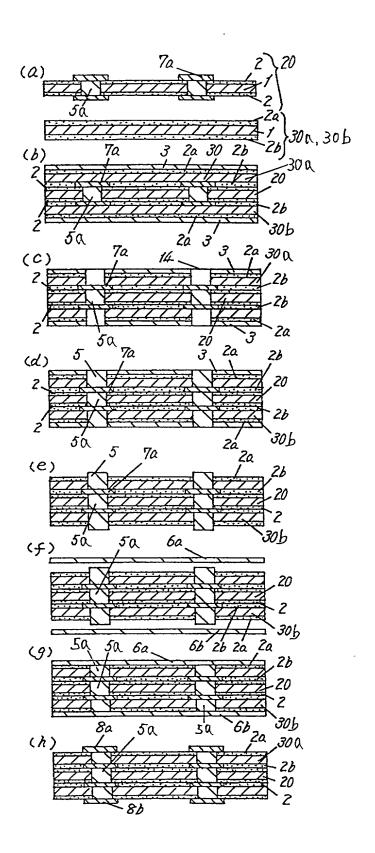
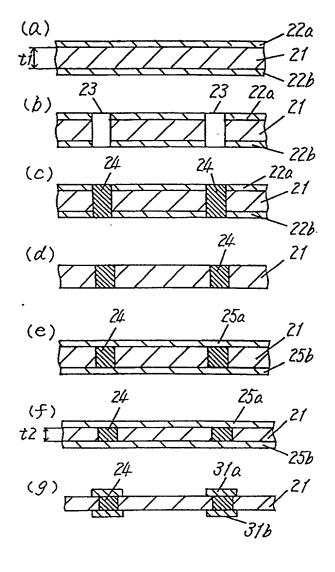


Fig. 7
PRIOR ART



F i g. 8

## PRIOR ART

